





#### 1. Features:

The features of LCD are as follows:

• Display mode: STN /BLUE, NEGATIVE, TRANSMISSIVE

• Colour: Display dot: WHITE

Background: BLUE

• **Display Format:** 16 (characters) ×2 (line)

• \* IC: ST7066 ST7065

• Interface Input Data: 8 Bits

• **Driving Method:** 1/16 Duty, 1/4 Bias

• Viewing Direction : 6 O'clock

• Backlight: LED (WHITE)

## 2. Mechanical Specifications:

Item	Specification	Unit
Module Size	80.00(W) X36.00(H) X12.0(T)	mm
Viewing Area	64.00(W) X 16.00(H)	mm
Effective Display Area	55.02(W) X 11.00(H)	mm
Number of Dots	$16$ (characters) $\times 2$ (line)	-
Dot Size	0.55(W) X 0.60(H)	mm
Dot Pitch	0.61(W) X 0.66(H)	mm

## 3. Electrical Specifications:

#### 1. Absolute Maximum Ratings (Vss = 0V)

Item	Symbol	St	Unit			
item	Cymbol	Min.	Тур.	Max.	Offic	
Supply Voltage for Logic	Vdd	-0.3	-	5.0	V	
Supply Voltage for LCD Drive	Vo, Vout	-0.3	-	14.5	V	
Operating Temp.	Тор	-20	-	+70	°C	
Storage Temp.	Тѕт	-30	-	+80	°C	
Static Electricity	Be sure that you are ground when handing LCM					

#### 2. Electrical Characteristics:

Item		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Supply Voltage	for Logic	VDD – VSS	Ta=25℃	4.8	5.0	5.2	<b>V</b>
Supply Voltage For LCD		VDD — Vo	<b>Ta=25</b> ℃	4.5	4.7	4.9	٧
	"H" Level	V <sub>IH</sub>	Ta=25°C	0.8V <sub>DD</sub>	-	Vdd	V
Input Voltage	"L" Level	V <sub>IL</sub>	1 <b>a-25</b> C	Vss	-	0.2VDD	V
Output Voltage	"H" Level	V oh	$I_{OUT} = -0.5 \text{mA}$	0.8VDD	-	VDD	V
Output voltage	"L" Level	V oL	I <sub>OUT</sub> = 0.5mA	Vss	-	0.2VDD	V
Current Cons	umption	I <sub>DD</sub>	$V_{IN} = V_{DD}$	-	-	1.0	mA

NOTE: 1) Duty ratio=1/65, Bias=1/9

2) Measured in Dots ON-state



#### 3. BACKLIGHT:

#### **3.1** Absolute Maximum Ratings:

Item	Symbol	Condition	Min.	Тур.	Max	Unit
Forward Current	IF	Ta= 25°C	-	-	20	mA
Reverse Voltage	VR	1a=25 C	-	-	5	V
Power Dissipation	PD	Ta= 25℃	-	-	100	mW

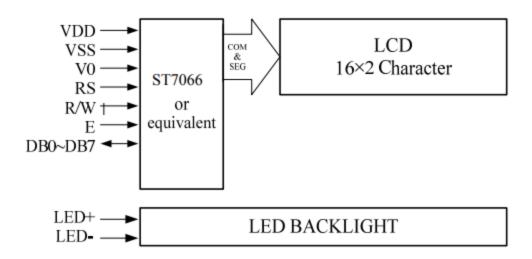
### **3.2** Opto-electronic Characteristics:

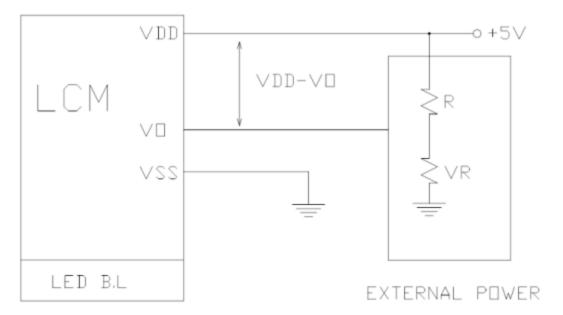
Item	Symbol	Condition	Min.	Тур.	Max	Unit
Forward Voltage	VF	Ta= 25℃	4.8	5.0	5.2	V
Luminous	-	IF= 32mA	100	150	-	cd/m²

<sup>\*</sup> The brightness is measured without LCD panel



## 4. Schematic Design:





VDD-VO:LCD DRIVING VOLTAGE
VR: 10K ~ 20K
IF VOP(LCD) > 5.0V,THE EXERNAL POWER MUST BE USED



## **5. Interface Pin Function:**

Pin No.	Pin Out	Description
1	VSS	GND
2	VDD	Logic supply voltage (5.0V)
3	vo	Power supply for LCD
4	RS	Data/Instruction RS=high: Indicates that data of DB0~DB7 is display data. RS=low: Indicates that data of DB0~DB7 is instruction
5	R/W	Read/Write R/W=high: Data of DB0~DB7 can be read by CPU. R/W=low: Data of DB0~DB7 can be written into LCD driver IC
6	E	Enable When write(R/W=low): Data of DB0~DB7 is latched at the fall of E When read(R/W=high): Data is read while E is at high level.
7	DB0	
8	DB1	
9	DB2	
10	DB3	Data Bus line.
11	DB4	
12	DB5	
13	DB6	
14	DB7	
15	A	LED Backlight +.
16	K	LED Backlight



## 6. Command List:

#### Instruction Table:

Instruction Tab				Instr	ructi	on (	Code	•				Description
Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description	Time (270KHz)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from AC	1.52 ms
Return Home	0	0	0	0	0	0	0	0	1	х	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.52 ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	s	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	37 us
Display ON/OFF	0	0	0	0	0	0	1	D	С	В	D=1:entire display on C=1:cursor on B=1:cursor position on	37 us
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	x	x	Set cursor moving and display shift control bit, and the direction, without changing DDRAM data.	37 us
Function Set	0	0	0	0	1	DL	N	F	x	х	DL:interface data is 8/4 bits N:number of line is 2/1 F:font size is 5x11/5x8	37 us
Set CGRAM address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter	37 us
Set DDRAM address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter	37 us
Read Busy flag and address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0 us
Write data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAWCGRAM)	37 us
Read data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAWCGRAM)	37 us

#### Note:

Be sure the ST7066U is not in the busy state (BF = 0) before sending an instruction from the MPU to the ST7066U. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself. Refer to Instruction Table for the list of each instruction execution time.



### NO.7066-0E 67-64 63-60 0000 0001 0010 0011 0100 0101 0110 0111 1000 1001 1010 1011 1100 1101 1110 1111 CG 0000 RAM (1) (2) 0001 U 0010 (3) 0011 (4) 0100 (5) 0101 (6) 0110 (7) W 0111 (8) 1000 (1) 1001 (2) (3) 1010 (4) 1011 (5)1100 (6) 1101 (7) 1110 (8) 1111



## 7. Timing Characteristics (Continued):

## AC Characteristeics (VDD = 2.7 V $\sim$ 4.5 V,Ta= -30 $\sim$ +85°C)

Mode	Characteristeics	Symbol	Min	Тур	Max	Unit
	Clock Pulse Width (Hight, Low)	Tc	500	-	-	
Interface Mode	Clock Rise / Fall Time	Tr,Tf	-	-	20	
With	Clock Setup Time	Tsu1	500	-	-	
Extension Driver	Data Setup Time	Tsu2	300	-	-	ns
(Refer to Fig-8)	Data Hold Time	Tdh	300	-	-	
	M Delay Time	TDM	-1000	-	1000	

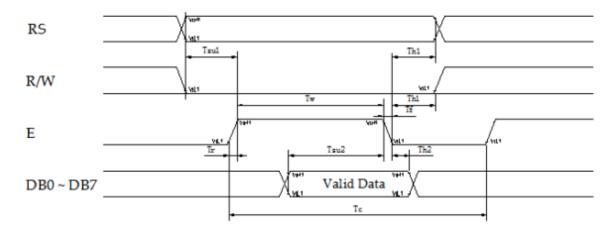


Figure 6. Write Mode Timing Diagram



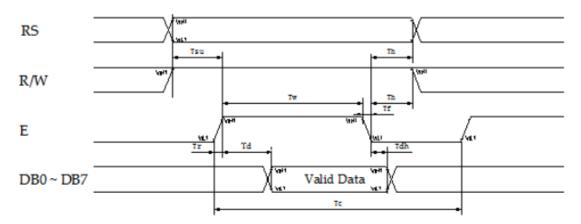


Figure 7. Read Mode Timing Diagram

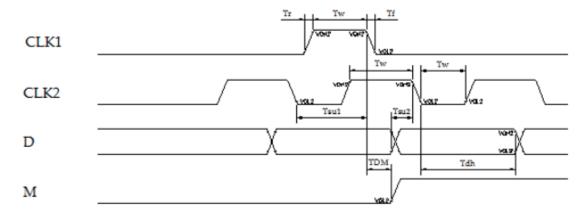


Figure 8. Interface Mode With Extension Driver Timing Diagram





# 8. Quality Specification (Continued):

#### 8-3. Sampling Plan and Acceptance

#### 1. Sampling Plan

MIL - STD - 105E (  $\blacksquare$  ) ordinary single inspection is used.

#### 2. Acceptance

Major defect: AQL = 0.25%Minor defect: AQL = 0.65%

#### 8-4. Criteria

#### a) COB

Defect	Inspection Item Inspection Standards			
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm <sup>2</sup>	Reject	
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject	
Major	Void or hole of coating epoxy	ing epoxy Expose bonding wire or IC		
Major	PCB cutting defect	Exceed the dimension of drawing	Reject	

#### b) SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing, extra, wrong component or wrong orientation		Reject
Minor	Component position shift	X < 3/4Z Y > 1/3D	Reject Reject
Minor	soldering pad Component tilt	Y > 1/3D	Reject



Minor	Insufficient solder  component PAD	θ ≤ 20'	Reject
	РСВ		

### c) Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards					
Major	Crack / breakage	Anywhere	e	Reject			
		W	L	Acceptable of Scratch			
		w<0.03mm	Any	Ignore			
		0.03mm <u>&lt;</u> w<0.05mm	L <u>&lt;</u> 5.0mm	2			
Minor	Frame Scratch	0.05mm <w<0.1mm< td=""><td>L&lt;3.0mm</td><td>1</td></w<0.1mm<>	L<3.0mm	1			
		w>0.1mm	Any	0			
		Note: 1. Above criteria applicable to scratch lines with distance greater than 5mm.  2. Scratch on the back side of frame (not visible) can be ignored.					
				Acceptable of Dents / Pricks			
		Φ <u>&lt;</u> 1.0mr	m	2			
		1.0<⊕ <u>&lt;</u> 1.5	mm	1			
	Frame Dent, Prick	1.5mm>	Þ	0			
Minor	$\Phi = \frac{L + W}{2}$	pricks with distance gr	Above criteria applicable to any two dents / ith distance greater than 5mm . Dent / prick on the back side of frame (not can be ignored				
Minor	Frame Deformation	Exceed the dimension of drawing					
Minor	Metal Frame Oxidation		Any rust				



#### d) Flexible Film Connector (FFC)

Defect	Insp	ection Item	Inspection Standards		
Minor	Tilted soldering		Within the angle ±3°	Acceptable	
Minor	Uneven solder joint /bump			Reject	
	$\Phi = L + W$		Expose the conductive line	Reject	
Minor Hole $\Psi^{\pm}$		2	Φ > 1.0mm	Reject	
	Po	sition shift	Y > 1/3D	Reject	
Minor			X > 1/2Z	Reject	

#### e) Screw

Defect	Inspection Item	Inspection Standards	
Major	Screw missing/loosen		Reject
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screwdriver	Reject

### f) Heat seal 、TCP 、FPC

Defect	Inspection Item	Inspection Standards		
Major	Scratch expose conductive layer		Reject	
Minor	HS Hole $\Phi = \frac{L + W}{2}$	Φ > 0.2mm	Reject	
Major	Adhesion strength	Less than the specification	Reject	
Minor	Position shift	Y > 1/3D	Reject	
		X > 1/2Z	Reject	
Major	Conductive line break		Reject	



### g) LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards			
		Acceptable number of units			
		Ф <u>&lt;</u> 0.10mm	Ignore		
		0.10<⊕ <u>&lt;</u> 0.15mm	2		
Minor	LED dirty, prick	0.15<⊕ <u>&lt;</u> 0.2mm	1		
		Ф>0.2mm	0		
		The distance between any two spots should be >			
		Any spot/dot/void outside of viewing area is acceptable			
Minor	Protective film tilt	Not fully cover LCD	Reject		
Major	COG coating	Not fully cover ITO circuit	Reject		

### h) Electric Inspection

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject



## i) Inspection Specification of LCD

Defect			Inspection Standards							
		* Glass Scratch	W		W<0.03		0.0	0.03 <w<0.05< td=""><td>W&gt;0.05</td></w<0.05<>		W>0.05
Minor			ACC.	L<5		L<3		Any		
	Linear Defect	* Polarizer Scratch	NO.	1			1		Reject	
		<ul><li>Fiber and Linear material</li></ul>	Note	L is th	L is the length and W is the width of the defect					ect
		* Foreign material	Ф	Φ <u>&lt;</u> 0.1 0.1<Φ <u>&lt;</u> 0.15 0.15<Φ <u>&lt;</u> 0.2			0.2	Ф>0.2		
	Black Spot and	between glass and polarizer or glass	ACC. NO.	3ЕА	/1PC	C 2		1		0
Minor	Polarizer Pricked	* Polarizer hole or protuberance by external force	Note	$\Phi $ is the average diameter of the defect. Distance betwee two defects > 10mm.					stance between	
		* Unobvious	Ф	Φ<	0.1	0.1<Φ<	1<Φ <u>&lt;</u> 0.15 0.15<Φ <u>&lt;</u> 0.2		:0.2	Ф>0.2
		transparent foreign material between	ACC. NO.		/ 1PC	2		1		0
Minor	White Spot and Bubble in polarizer	glass and glass or glass and polarizer  * Air protuberance between polarizer and glass	Note		<ul> <li>         Φ is the average diameter of the defect. Distance between two defects &gt; 10mm.     </li> </ul>				stance between	
			Φ	Φ <u>&lt;</u>	0.10	0.10<⊕ <u>&lt;</u> 0.20				Ф>0.2
	Segment Defect	w w	ACC. NO.	3ЕА	3EA/1PC 2				0	
Minor				W is more than 1/2 segment width			Reject			
Willion			Note	$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm						
		5 4	Ф	Φ	<u>&lt;</u> 0.10		0.10	<⊕ <u>&lt;</u> 0.20		Ф>0.2
	Protuberant	Segment			Glue W <u>&lt;</u> 1/2 Seg , W <u>&lt;</u> 0.2		2	Ignore		
Minor	Segment			3EA/1PC 2			0			
		Φ = (L+W)/2		1. Segment						
Minor			В	B B <u>&lt;</u>			0.4 <b<u>&lt;1.0mm</b<u>		B>1.0mm	
	Assembly Mis-		B-A		B-A<					B-A<0.25
		S- B A		e					Acceptable	
	alignment	0.35mm		2. Dot Matrix						
				Deformation>0.35mm Reject				Reject		



Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the aboveitems: "Black spot" and "White Spot"
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## 9. Reliability:

NO.	ltem	Condition	Criterion	
1	High Temperature Operating	70℃, 96Hrs		
2	Low Temperature Operating	-20℃, 96Hrs		
3	High Humidity	40℃, 90%RH, 96Hrs		
4	High Temperature Storage	80℃, 96Hrs	No defect in cosmetic	
5	Low Temperature Storage	-30℃, 96Hrs	and operational function allowable.	
6	Vibration	Random wave  10 ~ 100Hz  Acceleration: 2g  2 Hrs per direction(X,Y,Z)	Total current Consumption should be below double of initial value.	
7	Thermal Shock	-10℃ to 25℃ to 60℃ (60Min) (5Min) (60Min) 16Cycles		
8	ESD Testing	Contract Discharge Voltage: +1 ~ 5kV and -1 ~ -5kV  Air Discharge Voltage: +1 ~ 8kV and -1 ~ -8kV	There will be discharged ten times at every discharging voltage cycle. The voltage gap is 1kV.	

*Note:* 1) Above conditions are suitable for xinnuoya standard products.

2) For restrict products, the test conditions listed as above must be revised.



### 10. Handling Precaution:

#### (1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizerswhich easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

#### (2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommendedbelow) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichlorotrifloroethane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before poweris turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

- (4) Packaging
- Modules use LCD elements and must be treated as such. Avoid intense shockand falls from a height.
- To prevent modules from degradation. Do not operate or store them exposeddirectly to sunshine or high temperature/humidity.
- (5) Caution for operation
- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.

### **RG1602**



### DISPLAY 16×2 (View Area Wider) BLUE

- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show darkcolor in them. However, those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 60°C, 90% RH or less is required.

(6) Storage

In the case of storing for a long period of time (for instance, for years) for thepurpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
- It is recommendable to crash damaged or unnecessary LCD into pieces and washoff liquid crystal by using solvents such as acetone and ethanol.

Which should be burned up later.

When any liquid crystal leaked out of a damaged glass cell comes in contact withyour hands, please wash it off well with soap and water.



### 11. Outline Dimensions:

